Dual Inverter

The NLU2G04 MiniGate $^{\text{m}}$ is an advanced high-speed CMOS dual inverter in ultra-small footprint.

The NLU2G04 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.5 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

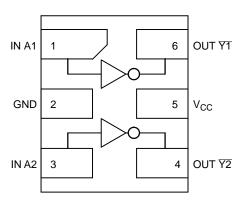


Figure 1. Pinout (Top View)

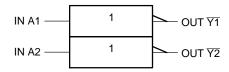


Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1			
2	GND			
3	IN A2			
4	OUT \(\overline{Y2} \)			
5	V _{CC}			
6	OUT <u>Y1</u>			

FUNCTION TABLE

H L



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MARKING DIAGRAMS



UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.45 x 1.0 CASE 517AQ



H = Device MarkingM = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Paramete	er	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V	
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	±20	mA
Ι _Ο	DC Output Source/Sink Current	±12.5	mA	
I _{CC}	DC Supply Current Per Supply Pin	±25	mA	
I _{GND}	DC Ground Current per Ground Pin	±25	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10 Se	conds	260	°C
TJ	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen	Index: 28 to 34	UL 94 V-0 @ 0.125 in	
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below C	GND at 125 °C (Note 2)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

2. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free–Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ \begin{array}{c} V_{CC} = 3.3 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \\ \end{array} $	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T	_A = 25 °	С	T _A = -	+85°C		55°C to !5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		1.65	0.75 x V _{CC}			0.75 x V _{CC}				٧
			2.3 to 5.5	0.70 x V _{CC}			0.70 x V _{CC}				
V _{IL}	Low-Level Input Voltage		1.65			0.25 x V _{CC}		0.25 x V _{CC}		0.25 x V _{CC}	V
			2.3 to 5.5			0.30 x V _{CC}		0.30 x V _{CC}		0.30 x V _{CC}	
V _{OH}	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu\text{A}$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu\text{A}$	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μА
lcc	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		40	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

		V _{CC}	Test	Т,	_A = 25 °	С	T _A = +	-85°C	T _A = -5 +12		
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	3.0 to	C _L = 15 pF		4.5	7.1		8.5		10.0	ns
t _{PHL}	Input A to Output \overline{Y}	3.6	C _L = 50 pF		6.4	10.6		12.0		14.5	i
		4.5 to	C _L = 15 pF		3.5	5.5		6.5		8.0	
		5.5	C _L = 50 pF		4.5	7.5		8.5		10.0	
C _{IN}	Input Capacitance				4	10		10		10.0	pF
C _{PD}	Power Dissipation Capacitance (Note 3)	5.0			8.0						pF

^{3.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

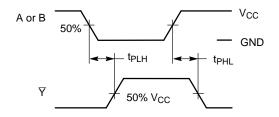
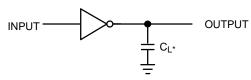


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance.

A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NLU2G04MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU2G04AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU2G04CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



△ aaa C

UDFN6, 1.20x1.00x0.50, 0.40P CASE 517AA ISSUE E

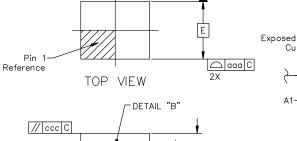
DATE 09 MAY 2025

NOTES:

- 1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.

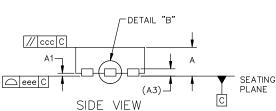
·Mold Compound

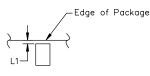
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL.
- 4. COPLANARITY APPLIES TO TH EXPOSED PAD AS WELL AS THE TERMINALS.



В

D





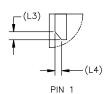
DETAIL "A" Scale 2:1 Bottom View (Optional)

DETAIL "B"

Scale 2:1

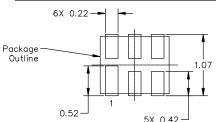
Side View

(Optional)



Chamfer Dimension

MILLIMETERS DIM MIN NOM MAX0.45 0.55 Α 0.50 Α1 0.00 0.05 ____ 0.127 REF А3 0.15 0.20 0.25 b D 1.20 BSC Ε 1.00 BSC 0.40 BSC е 0.30 0.35 0.40 L L1 0.00 ___ 0.15 L2 0.40 0.45 0.50 L3 0.14 REF L4 0.116 REF TOLERANCE FORM & POSITION aaa 0.10 bbb 0.10 CCC 0.10 ddd 0.05 eee 0.08



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb—Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

		/ DI	ETAIL "A"
•	1	3/	
L2	ЦΨ		5X L
• -	6	4 4 e	T
6X b	-	·	
^Ψ ddd C B(MOTTC	VIEW	

_	ENER	IC AGRAM*
	VVN4	

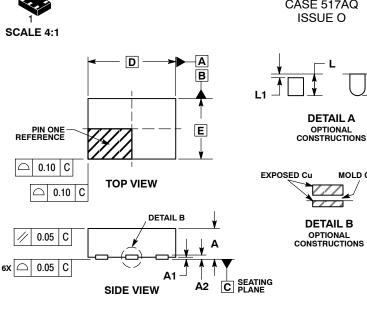
XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	UDFN6, 1.20x1.00x0.50, 0.4	UDFN6, 1.20x1.00x0.50, 0.40P			

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6X L

6X b

Ф

0.10 | C | A | B

0.05 C NOTE 3

UDFN6, 1.45x1.0, 0.5P CASE 517AQ **ISSUE O**

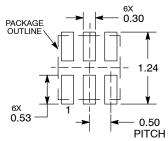
MOLD CMPD

DATE 15 MAY 2008

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS						
DIM	MIN MAX						
Α	0.45	0.55					
A1	0.00	0.05					
A2	0.07 REF						
b	0.20	0.30					
D	1.45 BSC						
Е	1.00 BSC						
Ф	0.50 BSC						
L	0.30	0.40					
L1		0.15					

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW

е



Χ = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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UDFN6, 1x1, 0.35P CASE 517BX **ISSUE O**

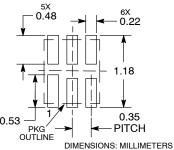
DATE 18 MAY 2011

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.20 MM FROM TERMINAL TIP. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00	0.05	
A3	0.13 REF		
b	0.12	0.22	
D	1.00 BSC		
E	1.00 BSC		
е	0.35 BSC		
L	0.25	0.35	
L1	0.30	0.40	

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

AB PIN ONE REFERENCE E 0.10 0.10 C **TOP VIEW** 0.05 C 0.05 C C SEATING SIDE VIEW 5X L

GENERIC MARKING DIAGRAM*

BOTTOM VIEW

0.10 M C A B

0.05 M C NOTE 3



X = Specific Device Code

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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